

WHAT IS CLAIMED IS:

- 5 1. An electro-conductive metal plated polyimide
 substrate comprising an aromatic polyimide substrate, a
 subbing metal layer of Mo-Ni alloy comprising molybdenum
 and nickel in a weight ratio of 75/25 to 99/1, and a
 plated electro-conductive film.
- 10 2. The electro-conductive metal plated polyimide
 substrate of claim 1, in which the subbing metal layer of
 Mo-Ni alloy comprises molybdenum and nickel in a weight
 ratio of 75/25 to 95/5.
- 15 3. The electro-conductive metal plated polyimide
 substrate of claim 1, in which the electro-conductive
 metal comprises copper.
- 20 4. The electro-conductive metal plated polyimide
 substrate of claim 1, in which the aromatic polyimide
 substrate has a surface having been subjected to plasma
 treatment under reduced pressure, said surface being in
 contact with the subbing metal layer.
- 25 5. The electro-conductive metal plated polyimide
 substrate of claim 4, in which the surface of the aromatic
 polyimide substrate has a protrusions dispersed to
 form a network of protrusions.
- 30 6. The electro-conductive metal plated polyimide
 substrate of claim 1, in which the aromatic polyimide
 substrate comprises a biphenyltetracarboxylic acid component
 and a phenylenediamine component.

7. The electro-conductive metal plated polyimide substrate of claim 1, in which the aromatic polyimide film comprises a high heat resistant aromatic polyimide core layer comprising a biphenyltetracarboxylic acid component and a phenylene diamine component, and a pair of flexible aromatic polyimide surface layers comprising polyimide having a flexible bonding in a molecular structure thereof.

8. The electro-conductive metal plated polyimide substrate of claim 1, in which the subbing metal layer of Mo-Ni alloy has a thickness in the range of 2 to 30 nm.

9. The electro-conductive metal plated polyimide substrate of claim 1, in which the electroconductive film has a thickness in the range of 0.05 to 30 μm .

10. The electro-conductive metal plated polyimide substrate of claim 1, in which a sputtered copper metal layer is provided between the subbing metal layer and the plated electro-conductive metal film.

11. The electro-conductive metal plated polyimide substrate of claim 1, which satisfies the following requirements:

said polyimide substrate does not show any change of appearance when it is placed in an alkaline etching solution containing 2 wt.% of NaOH for 5 min., at 50°C; and

said polyimide substrate keeps a surface insulation resistance of $4 \times 10^{10}\Omega$ or higher in either case that it is placed in a ferric chloride solution or a cupric chloride solution.